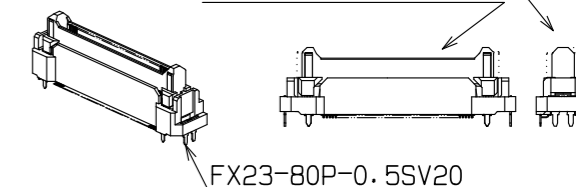


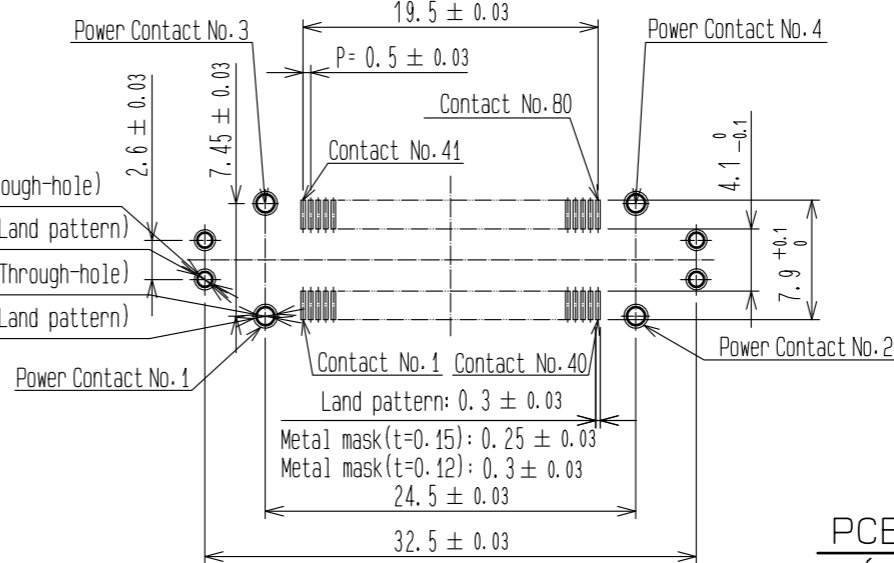
RECOMMENDED LAND PATTERN DIMENSION OF PCB
(PCB THICKNESS: $t=1.6\text{mm}$)

FLOATING RANGE

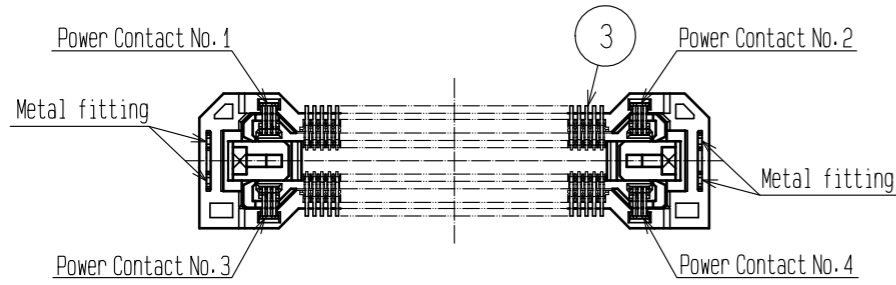
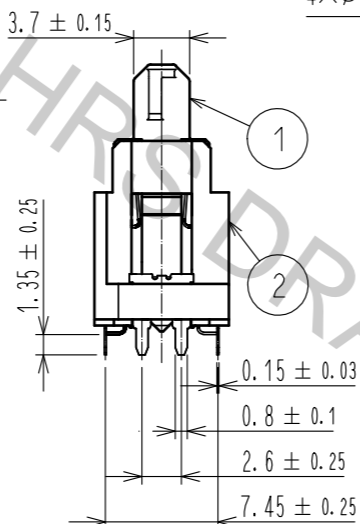
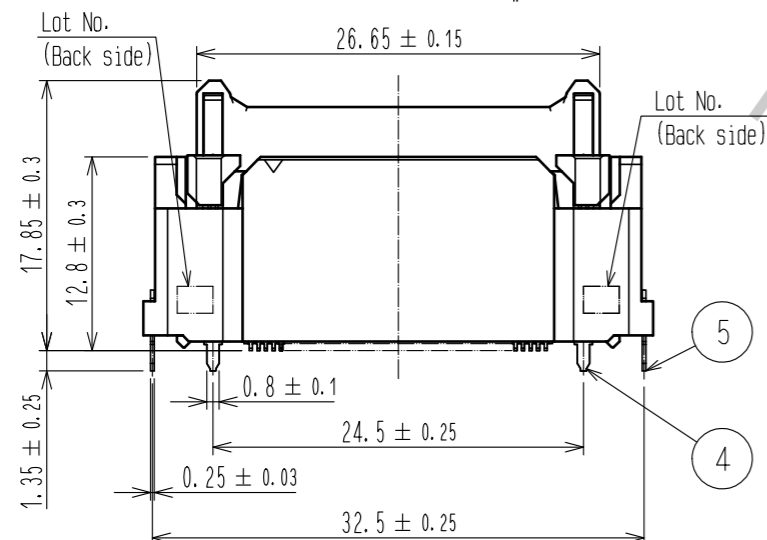
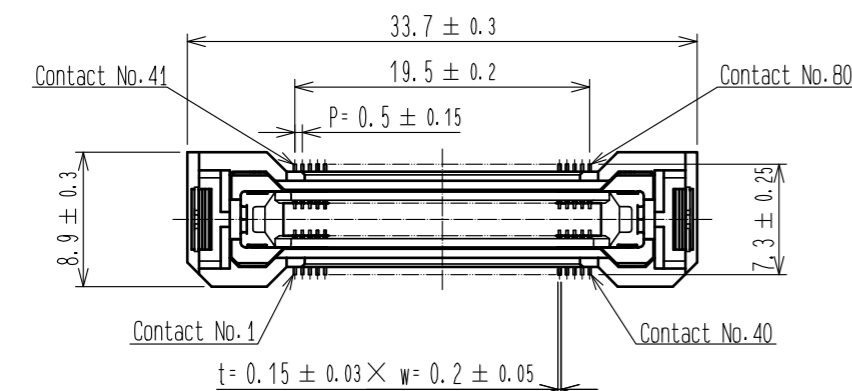
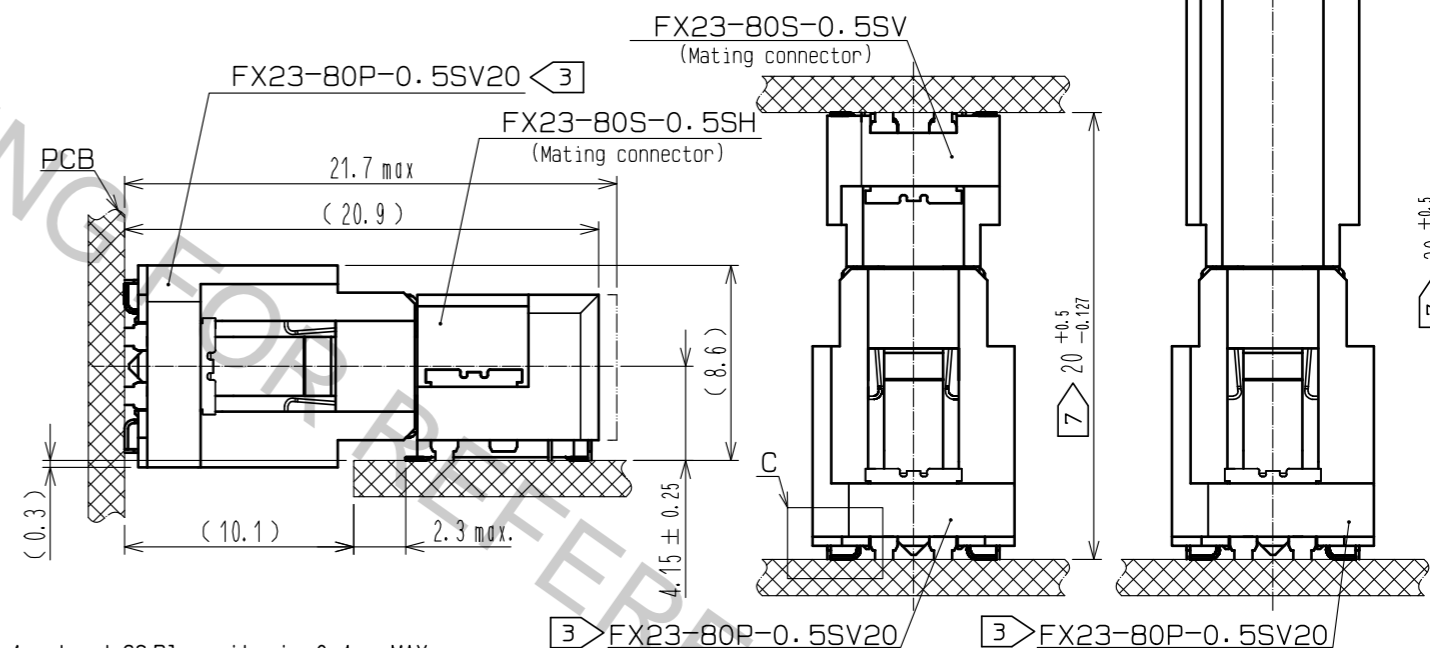
Y DIRECTION: $\pm 0.6\text{mm}$
X DIRECTION: $\pm 0.6\text{mm}$



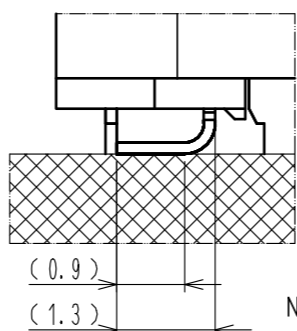
- $4 \times \phi 1^{+0.1}_0$ (Through-hole)
- $4 \times \phi 1.4^{+0.2}_0$ (Land pattern)
- $4 \times \phi 1.2^{+0.1}_0$ (Through-hole)
- $4 \times \phi 1.6^{+0.2}_0$ (Land pattern)



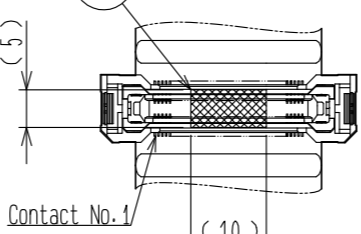
PCB DISTANCE
(No scale)



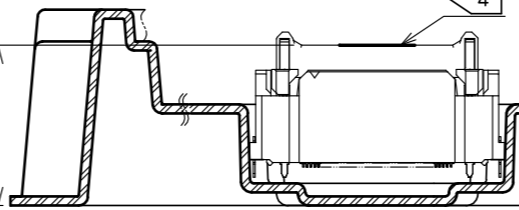
C (10 : 1)



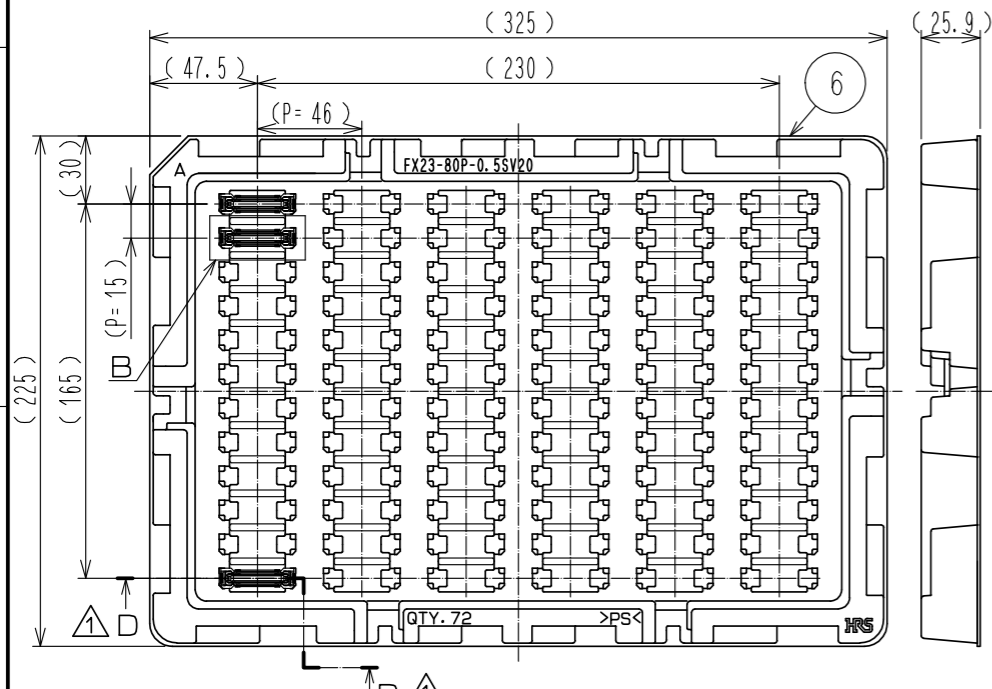
B (1 : 1)



D-D (1 : 1)



DRAWING FOR PACKING (No scale)



- Note
- 1 Lead CO-Planarity is 0.1mm MAX.
 - 2 This is packaged in tray. (72pcs/tray)
 - 3 Floating range of this connector is $\pm 0.6\text{mm}$ MAX.
 - 4 It shows the vacuum pickup area. Remove the mylar tape before mating connectors.
 - 5 Blemish and hit mark can be occurred through out the manufacturing process which doesn't affect quality level.
 - 6 The dimensions in parentheses are for references.
 - 7 Please use the connectors within the specified PCB distance.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: GOLD 0.03 μm UNDER PLATING: NICKEL 1.3 μm	7	POLYIMIDE		(TAPE FOR VACUUM PICKUP)
2	POLYAMIDE		BLACK UL94V-0	6	POLYSTYRENE		(TRAY)
1	POLYAMIDE		BLACK UL94V-0	5	BRASS		LEAD AREA: TIN-PLATING 3 μm UNDER PLATING: NICKEL 1 μm
				4	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: TIN-PLATING 1 μm UNDER PLATING: NICKEL 1.3 μm

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	4	DIS-F-00001099	TS.00NO	KN. SHIBUYA	16.02.17

APPROVED	DATE	DRAWING NO.
HS. OKAWA	14.11.08	EDC-353547-00-00
KN. SHIBUYA	14.11.08	PART NO. FX23-80P-0.5SV20
TS.00NO	14.11.08	CODE NO. CL573-3104-3-00
TS.00NO	14.11.08	